

MOSA, SOSA, and NO-SA: A Comparison of Chassis Platforms for MIL/Rugged Applications

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Common Design Challenges Across High-End MOSA, SOSA, and NO-SA Systems

- Higher wattage boards bringing thermal challenges:
 - Air cooled designs sometimes over 2300W
 - Conduction cooled designs often over 100W/slot, some cases more extreme
- Maximize RF/optical out to the panel
- SWaP requirements



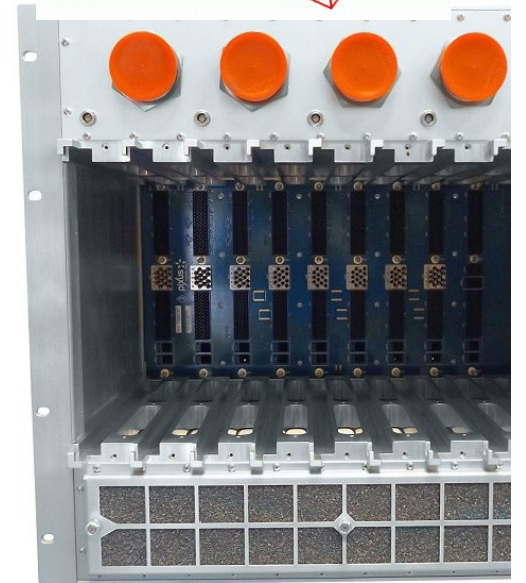
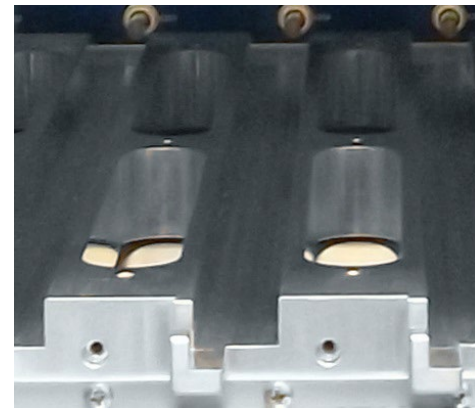
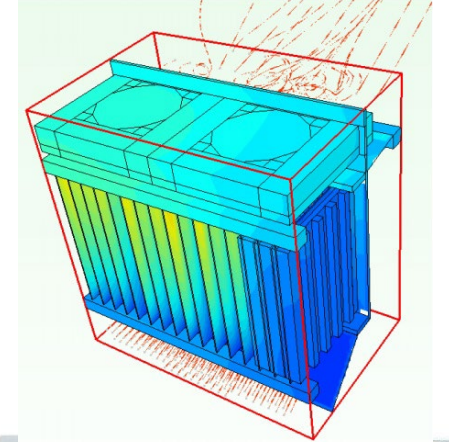
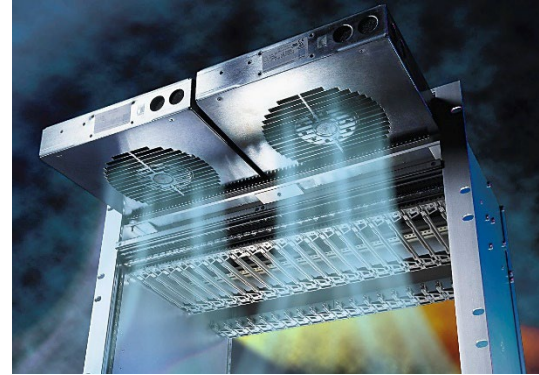
How Do We Cool These High Power Systems?



Original photo from Dodog

Cooling Solutions

- Optimized fan selection: balancing back-pressure, airflow, ruggedization, environment
- Thermal simulation to cool each slot properly, utilize baffling, spacing, etc.
- New Air Flow Through (VITA 48.8) or Air Flow By (VITA 48.7) techniques
- Liquid cooled (VITA 48.4). Often the last resort



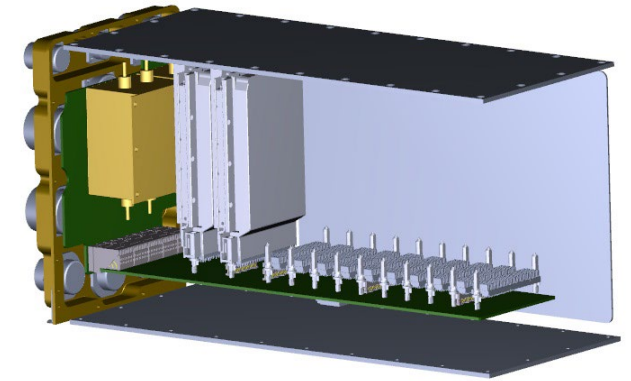
SOSA: Sensor Open Standard Architecture



SOSA: Key Backplane/Enclosure Parameters

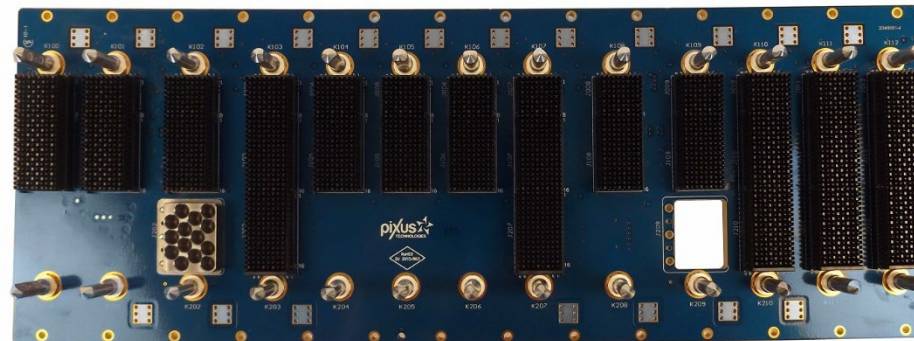
Key Elements of SOSA:

- SOSA Aligned profiles based on 3U/6U OpenVPX, often with fiber or optical interfaces
- Encapsulates CMOSS, FACE, HOST elements in one
- Often pushing performance barriers
- Speeds to PCIe Gen4 and 100GbE
- System management requirement



Challenges:

- Challenging thermal management, often higher than 100W/slot
- Backplane signal integrity at higher speeds and fiber/optical cutouts

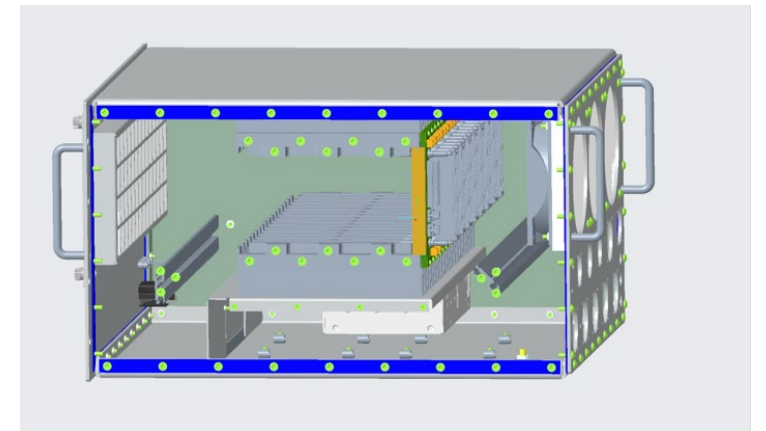
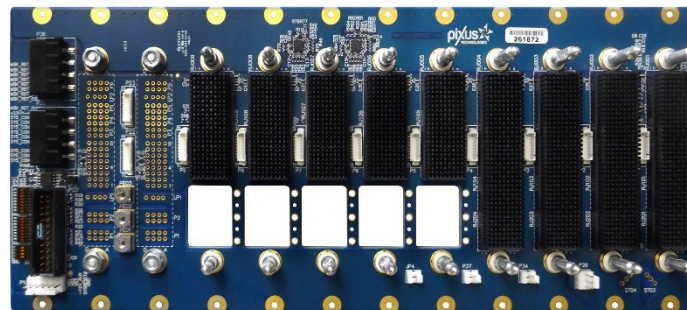
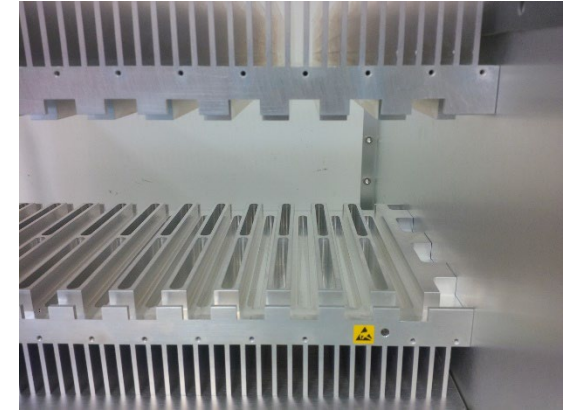


Application Example: 19" MIL Rugged Rackmount

6U Tall 19" MIL Rugged Rackmount, 3U
OpenVPX/SOSA Aligned Chassis

Addressing challenges:

- 100GbE (and PCIe Gen4) backplane with multiple P2 cutouts for RF/optical, backplane simulation
- Cooling of over 100W/slot, thermal simulation
- Advanced I/O implementation with multiple RF/optical interfaces, management of 38999 connectors spacing
- SOSA aligned shelf manager, often mezzanine type that does not consume any slots



MOSA: Modular Open Standard Architectures



MOSA: Key Backplane/Chassis Parameters

Key Elements of MOSA and MOSA-like:

- Open standard, but not a firm SOSA related requirement (Other OpenVPX, SpaceVPX, VME64x, CompactPCI/cPCI Serial, other)
- Sometimes very high performance, but others very basic levels (don't need SOSA performance)
- SOSA elements are often a plus, but not a requirement
- “Just make it work” vs a specific SOSA profile (ability to break the rules to achieve an objection)
- Broader range of applications typically

Challenges:

- Cooling and I/O management can be extreme
- Some cases with very high performance

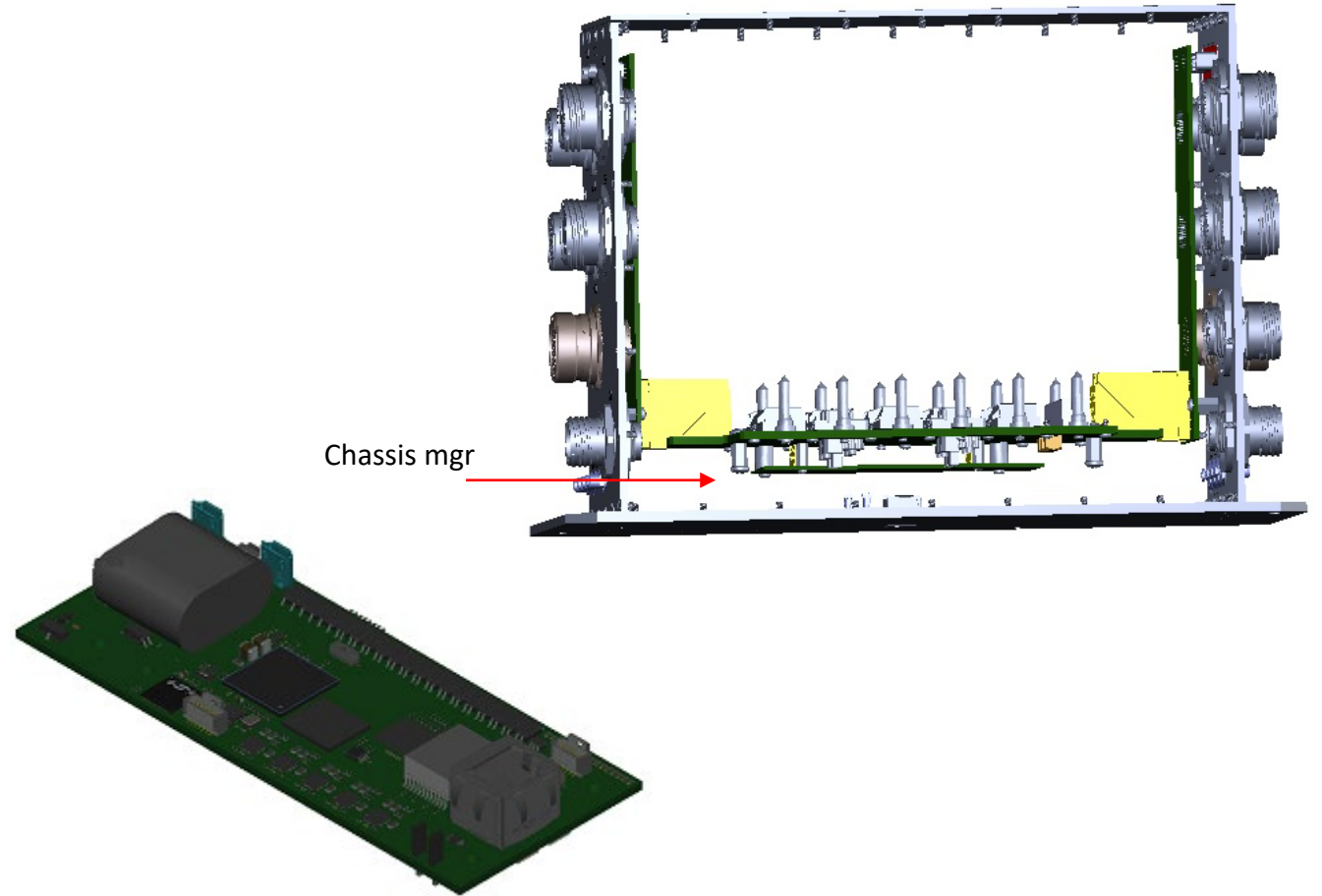


Application Example #1: SOSA Performance Not Key Driver, I/O Requirement

½ ATR 3U OpenVPX Chassis, Maximizing I/O Space

Addressing Challenges:

- Dual I/O boards double the panel space available (when allowed by application), some mirror-image, some not
- Saving space with SOSA Aligned SlotSaver Mezzanine-based Chassis & Hardware Manager below the backplane
- Fiber or RF through the backplane to panels, choosing optimal RF/fiber 38999 connectors
- All elements maximize space and reduce SWaP



Application #2: SOSA-like, Less Requirements to Reduce Costs

10U RiCool Chassis: Redundant Pluggable Power & Ultra-high Wattage

Addressing Challenges:

- Very similar to SOSA, but limited budget and scaled back functionality (PSUs, chassis mgmt)
- Data center type of application (not MIL rugged)
- Multiple boards over 200W, powerful dual 191 CFM hot swappable blowers
- Dual redundant pluggable power in rear, including 5V option
- Chassis management (more related to thermal/power, not individual boards), lower cost pluggable module



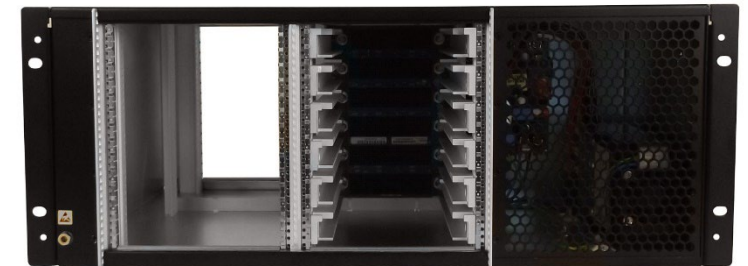
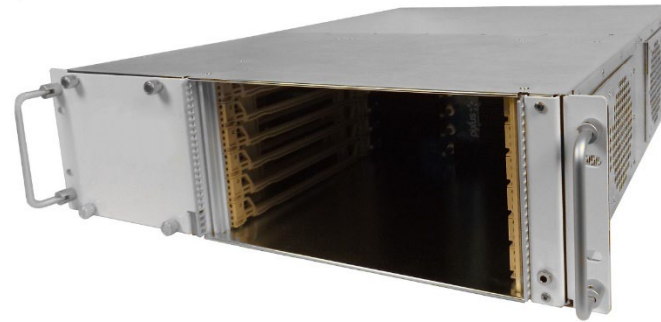
Board Power	Board Airflow	Loss coefficient	No of Slots
70W+	10 CFM	166.65	3
100W+	13.5 CFM	90.97	1
175W+	15 CFM	73.22	4
195-225W	25 CFM	26.6	5



Other Application Examples

Other Styles:

- 3U/6U hybrid OpenVPX
- VME/VME64x implementations
- OpenVPX ATR, but no SOSA needs
- Multi-bay 3U implementations
- Red/black implementation
- SpaceVPX



NO-SA: Specialty Architectures & Designs



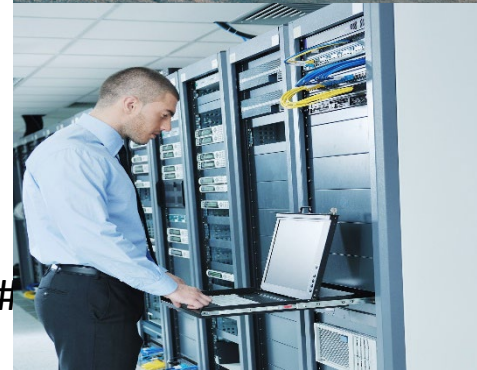
NO-SA: Key Board/Chassis Parameters

Key Elements of NO-SA:

- Application where modularity and standardization is not required
- Key driver such as only certain functional parameters (ie, small rugged enclosure) or cost
- Occasionally may have opposite requirement of extreme performance requirements (ability to break the “rules”)
- Wide range of application flexibility (communication systems, signal jamming/control, drone detection/deterrence, pole-mount & more)

Challenges:

- Extreme backplane performance
- Reducing SWaP
- Meeting MIL environmental (shock/vibration, -40C +71C, weather resistant)

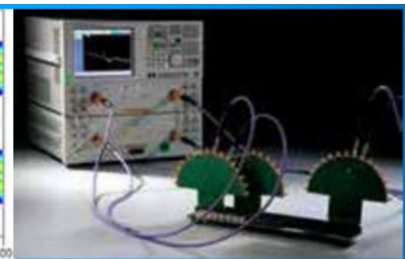
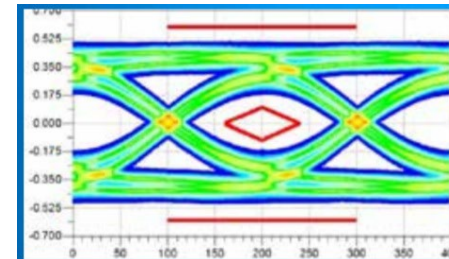
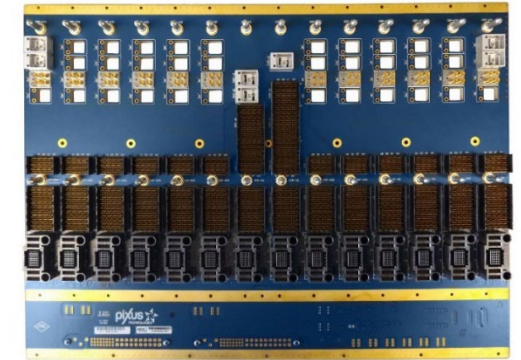


Application Example #1: Leverage OpenVPX, but Custom for Maximum Performance

Ultra High-speed Custom Chassis Design &
Advanced Cooling

Addressing Challenges:

- Speeds beyond 100GbE (28+G across backplane, high speed connector), backplane simulation
- OpenVPX electrically, but custom connectors to achieve speed levels
- 9U RiCool chassis w/dual powerful 191 CFM each hot swappable blowers for ~2200W of cooling
- Front-to-rear airflow
- Open area for RTM access and fiber/RF cabling



The Crowded Digital Battlefield

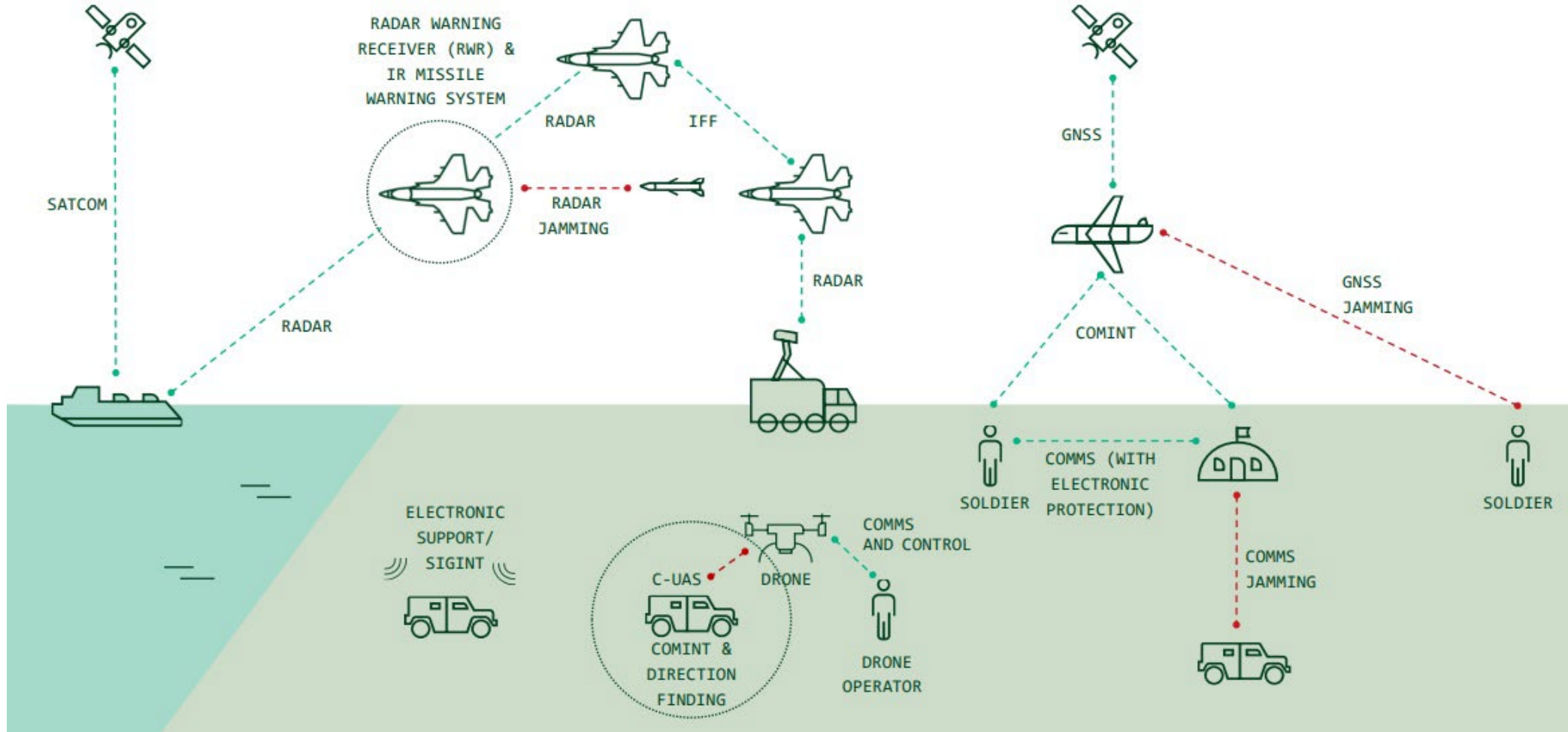


Image courtesy of NI

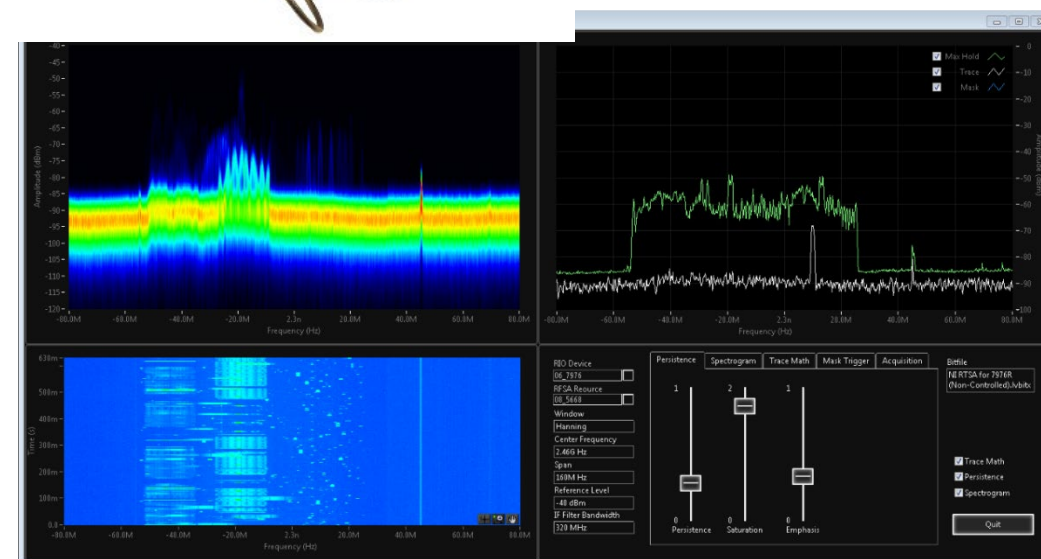
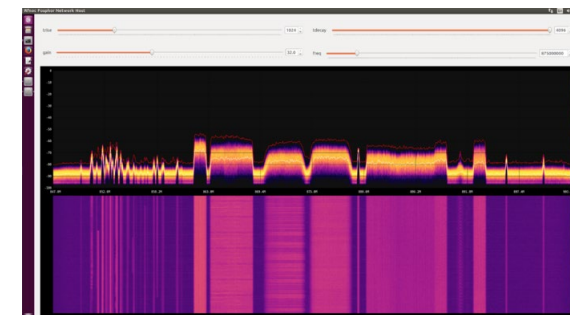


Application #2 Solution: Control the Wideband Spectrum Through Ruggedized Commercial SDRs

Ruggedized NI and custom SDRs

Addressing challenges:

- IP67 weatherproof or MIL rugged with 38999 interfaces
- Special heat-sink design to cool, options with heat/fan to meet extended temps
- Dual channel transceiver speeds to 100GbE
- Processors ranging from Zynq UltraScale+ to Spartan 6
- Often a PCIe Gen3 x8 interface
- Compact versions (lower performance for man-wearable applications), semi-rugged air cooled versions for Transport grade apps



Comparison of Chassis Classes

	SOSA	MOSA	NO-SA
High Performance	High	Medium to High	Low to High
Restrictions on Design Specification	High	Medium	Low
Configuration versatility	Medium	High	Low to Medium
Interoperability/Ease of integration	High	Medium	Low
Scalability/Future re-use	High	Medium	Low



Questions?

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